

04-27-2004

Attorney Docket No. 16869S-084200US

1 MAR 2004

Form PTO-1595
(Rev. 10-02)
OMB No. 0651-0027 (exp. 5/31/2002)



U.S. Department of Commerce
U.S. Patent and Trademark Office

To the Honorable Commission

attached original documents or copy thereof

1. Name of conveying party(ies):

102730380
3-21-04

2. Name and address of receiving party(ies)

Tasao SOGA
Hanae HATA
Toshiharu ISHIDA (deceased)
Tetsuya NAKATSUKA
Masahide OKAMOTO
Kazuma MIURA

Name: Hitachi, Ltd.

Street Address: 6, Kanda Surugadai 4-chome,
Chiyoda-ku, Tokyo

Country: Japan

Additional name(s) of conveying party(ies) attached? Yes No.

Additional name(s) and address(es) attached? Yes No

3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other:

Execution Date: 27 January 2004; 30 January 2004; 9 February 2004, 12 February 2004, and 20 February 2004

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No(s): 10/451,610 filed 20 June 2003

B. Patent No(s):

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

6. Total number of applications and patents involved: 1

Name: Robert C. Colwell
TOWNSEND AND TOWNSEND AND CREW LLP
Two Embarcadero Center, Eighth Floor
San Francisco, California 94111-3834
(415) 576-0200

7. Total fee (37 CFR 3.41): -----\$40.00

- Enclosed
- Authorized to be charged to deposit account

04/07/2004 GFREY1 00000125 201430 10451610
02/FC:8021 40.00 DA

8. Deposit account number: 20-1430

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Robert C. Colwell
Name of Person Signing
Atty. Reg. No. 27,431

Signature

31 March 2004
Date

Total number of pages including cover sheet, attachments and documents: 5

Mail documents to be recorded with required cover sheet information to:

Mail Stop Assignment Recordation Services
Director of the U.S. Patent and Trademark Office
P.O. Box 1450
Alexandria, VA 22313-1450

ASSIGNMENT (讓渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyodaku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SOLDER FOIL, SEMICONDUCTOR DEVICE AND ELECTRONIC DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	<u>Tasao Soja</u> Tasao SOGA	<u>9/February/2004</u>
2)	<u>Hanae Hata</u> Hanae HATA	<u>Jan. 30, 2004</u>
3)	<u>Toshiharu ISHIDA (Deceased)</u>	
4)	<u>Tetsuya Nakatsuka</u> Tetsuya NAKATSUKA	<u>27/January/2004</u>
5)	<u>Masahide Okamoto</u> Masahide OKAMOTO	<u>January 27, 2004</u>
6)	<u>Kazuma Miura</u> Kazuma MIURA	<u>12/February/2004</u>
7)	<u>Kanko Ishida</u> Kanko ISHIDA	<u>FEB. 20. 2004</u>
8)	<u>Heir to Toshiharu ISHIDA, deceased</u>	
9)		
10)		